Form 1449 (Modified) **Information Disclosure Statement By Applicant** (Use Several Sheets if Necessary)	Atty. Docket No. KLA1P083/P1039 Applicant: Delgado et al. Filing Date October 16, 2003	Application No.: 10/688,839 Group ~~2877~~ 2884

U.S. Patent Documents

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Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation Yes	Translation No
	J							

Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
DB	O	Wakamiya, "Status of 157nm Microstepper with High NA Lens," International Sematech, 157nm Technical Data Review dated May 7-9, 2002.
DB	P	Stokowski et al., "Wafer Inspection Technology Challenges for ULSI Manufacturing," KLA-Tencor.
DB	Q	"High-throughput scanning for patterned wafer inspection," http://www.kla-tencor.com/products/defect_control/aitxp/aitxp.html, downloaded June 11, 2002.
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DSB	S	"High-resolution imaging for patterned wafer inspection," http://www.kla-tencor.com/products/defect_control/2351/2351.html, downloaded June 11, 2002.
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DSB	X	Stokowski et al., "Wafer Inspection Technology Challenges for ULSI Manufacturing – Part II, Yield Management Solutions, August 1999.

Examiner	Date Considered
David A. Baker DAVID S. BAKER	31 MARCH 2006

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.